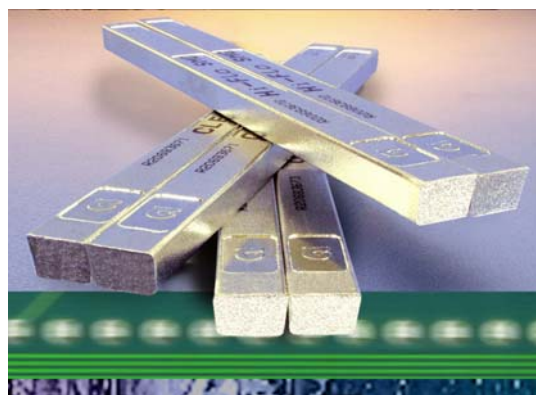


ALPHA CLEANWAVE WAVESOLDER METAL

- Very good wetting and soldering performance.
- Meets international specifications J-STD-006, ISO 9453, JIS Z3282A
- Includes proprietary dross reducing technology

General purpose wave soldering product



DESCRIPTION

CLEANWAVE is manufactured using high purity raw materials and is treated using proprietary dross reducing technology to give a solder alloy that has Low Dross Characteristics.

FEATURES & BENEFITS

- *Low Dross Characteristics:* giving cost effective use of the solder alloy.
- *Low Dross Characteristics:* reducing the amount of dross in the wave pot leading to lower downtime and reducing the chance of oxide entrapped in joints.
- *Manufactured to Alpha's high standards:* giving a product that can be relied on to give good consistent soldering performance.

APPLICATION

CLEANWAVE can be used in all wave soldering systems and will give excellent soldering performance and good value per joint.. A solder pot temperature of 240 - 250° is recommended. For suitable wave solder fluxes, please see our selector guide. Reclaim services including dedicated containers are also available, please consult your local sales office.

AVAILABILITY

CLEANWAVE is available in 3.5kg feeder bars, 1kg bars and solder chunks for first fill of solder baths.

HEALTH & SAFETY

Please refer to MSDS for advice on proper handling and safety instructions.

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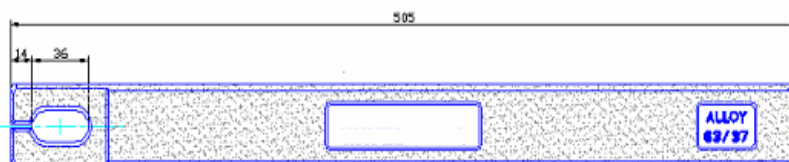
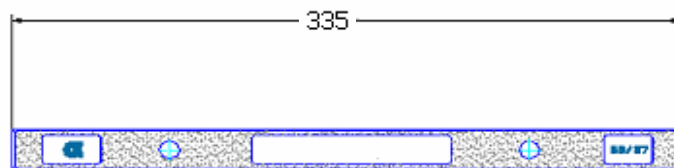
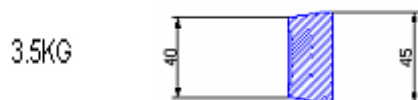
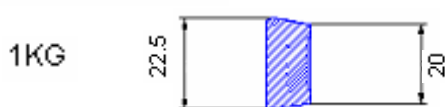
Cookson Electronics ASSEMBLY MATERIALS

Issue 3



DIMENSIONS OF BARS

All dimensions in mm



TECHNICAL SPECIFICATION

The following indicates the Alloy and impurity limits for CLEANWAVE in relation to J-STD-006A, ISO9453 and JIS Z3282.

ELEMENT	CLEANWAVE	ISO 9453 Alloy 1 ¹	J-STD-006A Sn63Pb37B ²	JIS Z3282A H63A ³
Sn	62.5-63.5	62.5-63.5	62.5-63.5	62.5-63.5
Pb	Balance	Balance	Balance	Balance
Sb	0.12 max	0.12 max	0.20 max	0.12 max
Cu	0.05 max	0.05 max	0.08 max	0.05 max
Zn	0.001 max	0.001 max	0.003 max	0.002 max
Fe	0.01 max	0.02 max	0.02 max	0.02 max
As	0.01 max	0.03 max	0.03 max	0.03 max
Ni	0.01 max	Not specified	0.01 max	Not specified
Bi	0.10 max	0.10 max	0.10 max	0.10 max
Cd	0.001 max	0.002 max	0.002 max	0.002 max
Ag	0.10 max	Not specified	0.10 max	Not specified
Al	0.001 max	0.001 max	0.005 max	0.002 max
In	0.05 max	Not specified	0.10 max	Not specified

All figures are %

1. ISO 9453: 1990

Soft Soldering Alloys - chemical composition and form. ISO - International Standards Organization, a network of national standards institutes working in partnership.

2. J-STD-006A: May 2001

Requirements for Electronic Grade Solder alloys and non-fluxed solders. Joint Industry Standard between IPC and Electronic Industries Alliance (US Based). IPC formed in 1957 as an Institute of Printed Circuits, J-STD-006A supercedes IPC-SF-818.

3. JIS Z3282:1999

Soft solders chemical composition and forms. JIS - Japanese Industrial Standard.



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